Silicon P Channel MOS FET High Speed Power Switching

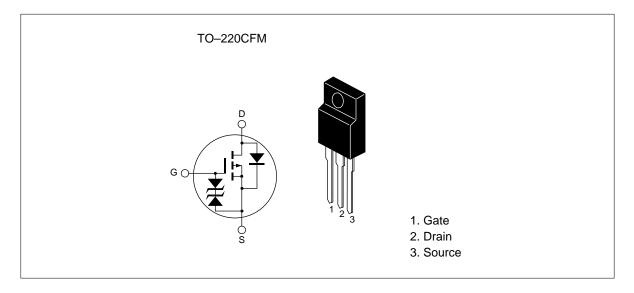


ADE-208-653B (Z) 3rd. Edition June 1, 1998

Features

- Low on-resistance
- $R_{DS(on)} = 0.042\Omega$ typ.
- Low drive current.
- 4V gate drive devices.
- High speed switching.

Outline



Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

m Symbol		Ratings	Unit	
Drain to source voltage	V _{DSS}	-60	V	
Gate to source voltage	V _{GSS}	±20	V	
Drain current	I _D	-20	A	
Drain peak current	Note1	-80	A	
Body-drain diode reverse drain current	I _{DR}	-20	A	
Avalanche current	AP Note3	-20	A	
Avalanche energy	E _{AR} ^{Note3}	34	mJ	
Channel dissipation	Pch Note2	30	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Note: 1. $PW \le 10\mu s$, duty cycle $\le 1 \%$

2. Value at Tc = $25^{\circ}C$

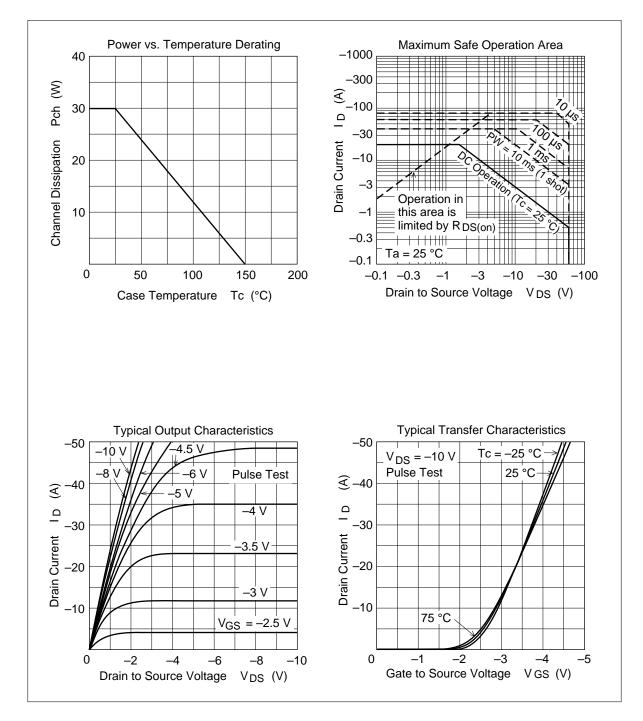
3. Value at Tch = 25° C, Rg $\geq 50 \Omega$

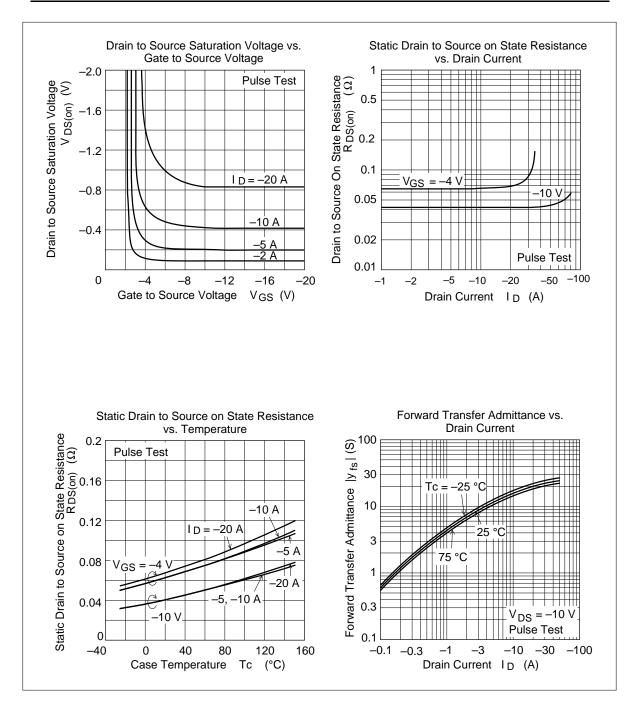
Electrical Characteristics (Ta = 25°C)

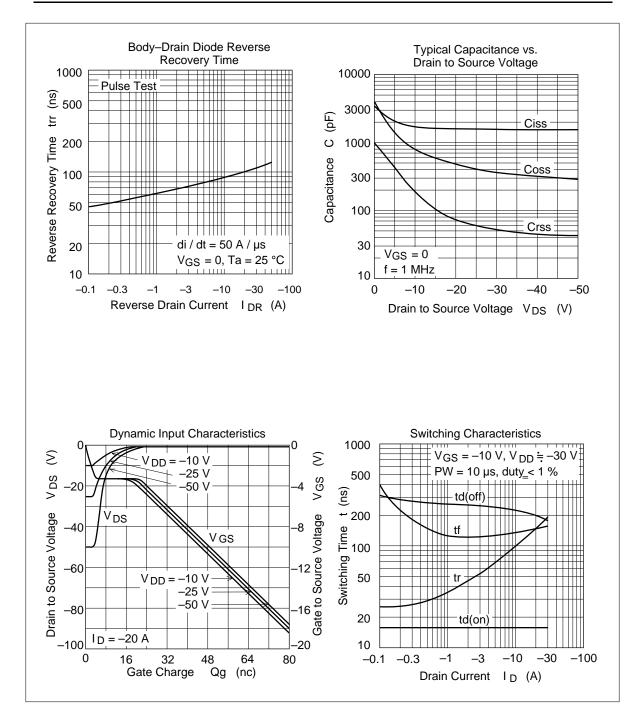
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR)DSS}	-60	_	_	V	$I_{\rm D} = -10$ mA, $V_{\rm GS} = 0$
Gate to source breakdown voltage	V _{(BR)GSS}	±20	_	_	V	$I_{g} = \pm 100 \mu A, V_{DS} = 0$
Zero gate voltege drain current	I _{DSS}			-10	μA	$V_{DS} = -60 \text{ V}, \text{ V}_{GS} = 0$
Gate to source leak current	I _{GSS}		_	±10	μΑ	$V_{GS} = \pm 16V, V_{DS} = 0$
Gate to source cutoff voltage	V _{GS(off)}	-1.0		-2.0	V	$I_{\rm D} = -1$ mA, $V_{\rm DS} = -10$ V
Static drain to source on state	R _{DS(on)}		0.042	0.055	Ω	$I_{\rm D} = -10$ A, $V_{\rm GS} = -10$ V ^{Note4}
resistance	$R_{DS(on)}$	_	0.065	0.095	Ω	$I_{\rm D} = -10$ A, $V_{\rm GS} = -4V^{\rm Note4}$
Forward transfer admittance	y _{fs}	10	16	_	S	$I_{\rm D} = -10$ A, $V_{\rm DS} = -10$ V ^{Note4}
Input capacitance	Ciss		1750		pF	$V_{DS} = -10V$
Output capacitance	Coss	_	800	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss		180	_	pF	f = 1MHz
Turn-on delay time	t _{d(on)}		16		ns	$V_{GS} = -10V, I_{D} = -10A$
Rise time	t,	_	100	_	ns	$R_L = 3\Omega$
Turn-off delay time	t _{d(off)}		230	_	ns	
Fall time	t _f	_	140	_	ns	
Body-drain diode forward voltage	V _{DF}	_	-1.0	_	V	$I_{\rm F} = -20$ A, $V_{\rm GS} = 0$
Body–drain diode reverse recovery time	t _{rr}		100		ns	$I_{F} = -20A, V_{GS} = 0$ diF/ dt =50A/ μ s

Note: 4. Pulse test

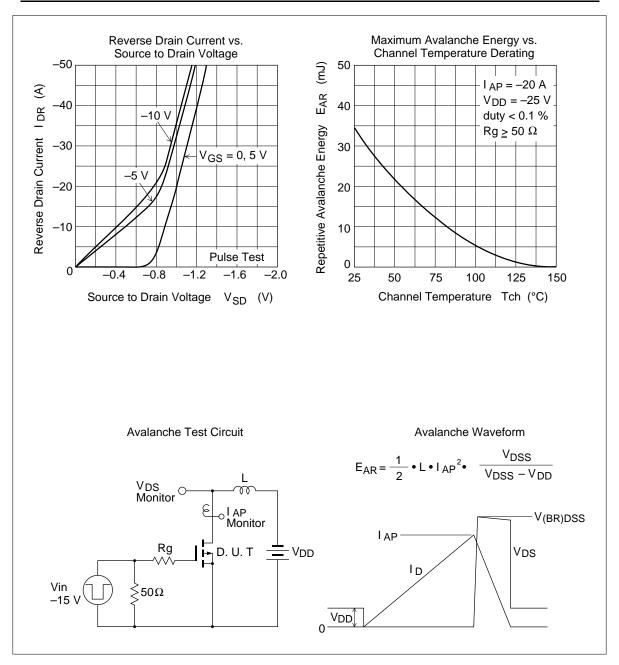
Main Characteristics

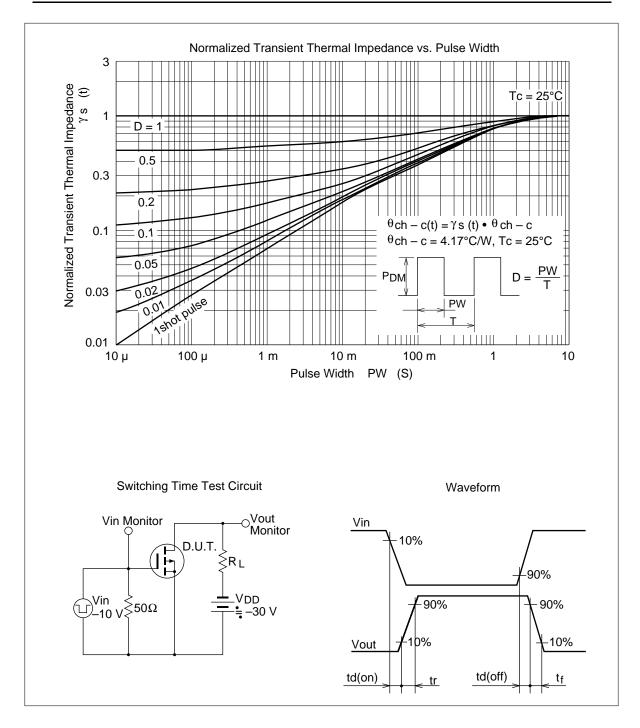




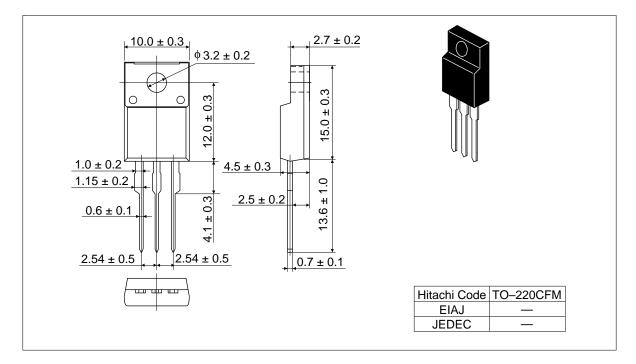


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Package Dimensions (Unit: mm)



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